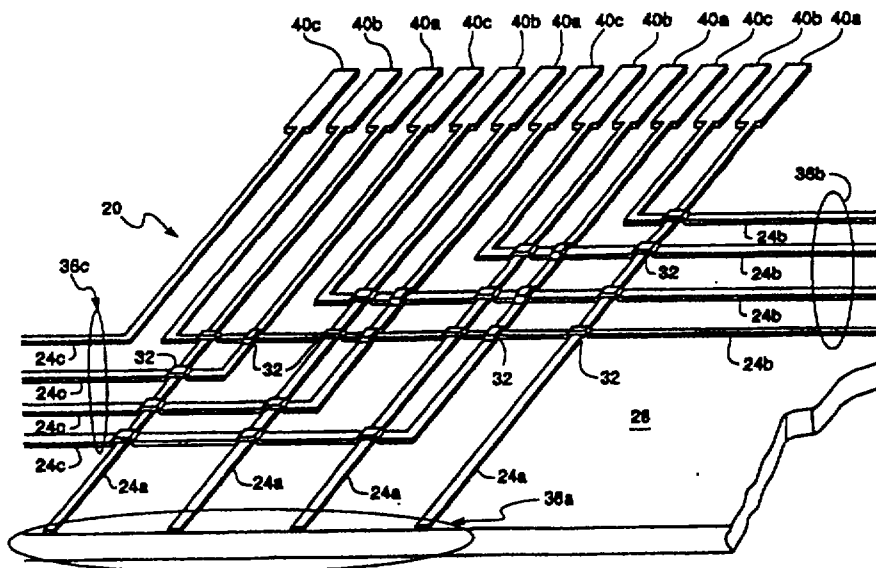




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(57) Abstract

A circuit board fabrication method in which circuit boards are fabricated by adhesively applying circuit conductive traces (24) to a circuit board substrate (28) and subsequently affixing the arrangement of the circuit traces (24) within a circuit board covering material that becomes flowable and adhesive when subjected to heat and pressure. Circuit traces (24) are created and applied to circuit board substrate (28) areas by a punch and die assembly. A sheet of circuit trace material is provided between plates of the apparatus wherein the plates have matching circuit trace shaped cut-outs. Punch elements having a mating circuit trace shape are slidable within the cut-outs wherein a circuit trace (24) is punched from the circuit trace material when the punch elements slide between the plates. After a circuit trace (24) is punched, the punch elements then stamp the circuit trace (24) to the substrate (28).